

BGA777L7E6327XTSA1 Information


For Reference Only

Part Number [BGA777L7E6327XTSA1](#)
Manufacturer Infineon Technologies
Category RF/IF and RFID
[RF Amplifiers](#)
Description IC AMP MMIC SGL-BAND LN TSLP7-1
Package 6-XFDFN Exposed Pad
 For the pricing/inventory/lead time, please contact us
 Website: <https://www.heisener.com>
 E-mail: salesdept@heisener.com


[Request a Quote](#)
Certified Quality

Heisener's commitment to quality has shaped our processes for sourcing, testing, shipping, and every step in between. This foundation underlies each component we sell.


BGA777L7E6327XTSA1 Specifications

Manufacturer Part Number	BGA777L7E6327XTSA1
Manufacturer	Infineon Technologies
Category	RF/IF and RFID RF Amplifiers
Package	6-XFDFN Exposed Pad
Series	-
Frequency	2.3GHz, 2.7GHz
P1dB	-11dBm
Gain	16.8dB
Noise Figure	1.2dB
RF Type	UMTS
Voltage - Supply	2.6 V ~ 3 V
Current - Supply	10mA
Test Frequency	2.3GHz
Package / Case	6-XFDFN Exposed Pad
Supplier Device Package	TSLP-7-1

[Report errors?](#)

BGA777L7E6327XTSA1 Guarantees



Quality Guarantees

We provide 90 days warranty. *

If the items you received were not in perfect quality, we would be responsible for your refund or replacement, but the items must be returned in their original condition.



Service Guarantees

We guarantee 100% customer satisfaction.

Our experienced sales team and tech support team back our services to satisfy all our customers.

BGA777L7E6327XTSA1 Payment Methods



BGA777L7E6327XTSA1 Shipping Methods



If you have any question about BGA777L7E6327XTSA1, please do not hesitate to contact us!

Website: <https://www.heisener.com>

E-mail: salesdept@heisener.com